Amendments to the Claims:

1-10. (Canceled)

11. (New) A method of testing the bond strength of an electrically conductive ball adhered to a substrate, and comprising the steps of gripping the ball with a test tool, moving the ball in a direction substantially orthogonal to the plane of adherence of the ball whilst urging the substrate lightly against the ball, and abruptly halting the substrate.

12. (New) The method of testing according to claim 11 and including the preparatory step of clamping the substrate to a platen, whereby the platen is abruptly halted, thereby indirectly halting the substrate.

13. (New) The method of testing according to claim 11 and including the step of providing a pneumatic ram to urge the substrate against the ball, and applying air under pressure to the ram in an amount sufficient to ensure a light compressive load between the ball and substrate up to the time when said substrate is abruptly halted.

14. (New) The method of testing according to claim 12 and including the step of providing a pneumatic ram to urge the substrate against the ball, and applying air under pressure to the ram in an amount sufficient to ensure a light compressive load between the ball and substrate up to the time when said substrate is abruptly halted.

15. (New) Apparatus for tensile testing of the bond of an electrically conductive ball adhered to a substrate, and comprising a frame, a gripper for gripping a ball adhered to a substrate, apparatus for moving said gripper on an axis substantially orthogonal to the plane of adherence, urging apparatus of said frame for lightly urging said substrate on said axis towards said gripper, and an abutment of said frame for said substrate, whereby in use the substrate and ball are adapted to move in unison on said axis until the substrate is restrained by said abutment.

16. (New) The apparatus according to claim 15 wherein said urging apparatus comprises a pneumatic ram.

17. (New) The apparatus according to claim 15 wherein said urging apparatus includes a platen for said substrate.

18. (New) The apparatus according to claim 16 wherein said urging apparatus includes a platen for said substrate.

19. (New) The apparatus according to claim 17 and further including a clamp device to releasably restrain a substrate on said platen.

20. (New) The apparatus according to claim 18 and further including a clamp device to releasably restrain a substrate on said platen.

21. (New) The apparatus according to claim 15 and adapted to provide said abutment by said direct contact between said frame and said ram.

22. (New) The apparatus according to claim 15 and adapted to provide said abutment by direct contact between said frame and substrate.

23. (New) The apparatus according to claim 17 and adapted to provide said abutment by direct contact between said frame and platen.

24. (New) The apparatus according to claim 18 and adapted to provide said abutment by direct contact between said frame and platen.

25. (New) The apparatus according to claim 19 and adapted to provide said abutment by direct contact between said frame and platen.

26. (New) The apparatus according to claim 20 and adapted to provide said abutment by direct contact between said frame and platen.